



APPLICATION NOTE 4059

DS33R41 Multichip-Module BSDL Testing

Abstract: This application note describes how to alter the printed wiring board (PWB) netlist of a design containing the DS33R41 Inverse-Multiplexing Ethernet Mapper with Integrated Quad Port T1/E1/J1 Transceiver so that the netlist complies with the Joint Test Action Group (JTAG) specifications. These changes are necessary because the DS33R41 was designed as a multichip module with multiple die in a single package which can not be defined by the Boundary-Scan Description Language (BSDL) for board level JTAG testing. The application note contains external pin mapping tables, internal die pad bond tables, and connection information allowing the designer to quickly achieve accurate JTAG boundary-scan board testing.

Introduction

When manufacturing hardware for a telecommunications system, one of the basic tasks is to test the system for any production flaws. While there are many ways to test the hardware, one of the most popular methods uses the Joint Test Action Group (JTAG) boundary-scan method. The boundary-scan test method involves some minor changes to the hardware before production so that hardware verification can be performed after production. During design, all of the Integrated Circuit (IC) devices which support JTAG are connected in a serial daisy-chain fashion through the JTAG test access port. Verification is done by a specialized JTAG test system which connects to the test access port. The JTAG test system then uses a combination of the printed wiring board (PWB) netlist, Boundary-Scan Description Language (BSDL) files, and PWB connectivity test vectors to verify the pin-to-pin connections.

BSDL testing is straightforward. Nonetheless, multichip module devices like the [DS33R41](#) Inverse-Multiplexing Ethernet Mapper with Integrated Quad Port T1/E1/J1 Transceiver cannot be properly described by a single BSDL file because there are multiple die in a single package. This shortcoming can be overcome with simple modification to the PWB netlist and by using two BSDL files to describe the device package instead of just one.

Modifying the Printed Wiring Board Netlist

Before JTAG boundary scan testing can be performed, the portion of the PWB netlist that describes the external connections to the DS33R41 package must be modified to split those connections between the internal [DS33Z41](#) die and [DS21458](#) die. Once completed, the netlist will define the DS33R41 package with two independent reference designators. These reference designators allow two different BSDL files to individually describe the DS33Z41 and DS21458 connections inside the DS33R41 package.

Tables 1, 2, and 3 and **Figure 1** make the task of modifying the netlist easy. Table 1 lists all of the external DS33R41 package pins which only connect to the DS33Z41 die. Table 2 lists all of the external DS33R41 package pins which only connect to the DS21458 die. Table 3 lists all of the external DS33R41 package pins which connect to both the DS33Z41 die and the DS21458 die. Figure 1 shows the same information in a format created for easier viewing.

This PWB netlist modification and JTAG boundary scan test have been performed using a Concise Net List format netlist of the DS33R41 engineering evaluation board designed with Cadence® Concept. Designers can perform the operation in approximately 30 to 60 minutes, depending on the netlist type and individual's skill level. Most of the edits to the netlist file can be done with a simple text editor. Depending on the netlist type, however, it may be possible to edit the netlist in a program such as Microsoft® Excel which can sort rows based on column data. However the editing is done, it is important to pay careful attention to detail. Irregular data such as header and footer information must be maintained, and the netlist must always be saved in the original format.

The following is a list of steps needed to complete the process.

1. Open the netlist file in a text editor and group all of the nets connected to the DS33R41 reference designator. As an example, the DS33R41 package on the DS33R41 Engineering Evaluation board had a reference designator of U01.
2. Separate all of the nets isolated in step 1 among those connected to the DS33Z41 die, those connected to the DS21458 die, and those connected to both dies. Use Tables 1, 2, and 3 and Figure 1 to complete this task.
3. Change the reference designator for all of the DS33Z41 nets from U01 to U01_D1 (short for reference designator U01, device 1). This step assumes that the DS33R41 reference designator was U01. If the reference designator is not U01, change U01_D1 appropriately.
4. Change the reference designator for all of the DS21458 nets from U01 to U01_D2 (short for reference designator U01, device 2). This assumes that the DS33R41 reference designator was U01. If it is not U01, change U01_D2 appropriately.
5. Duplicate the 22 shared nets so that there is exactly two of each. Split them into two groups.
6. Change the reference designator for first group of nets created in step 5 from U01 to U01_D1. This assumes that the DS33R41 reference designator was U01. If it is not U01, change U01_D1 appropriately.
7. Change the reference designator for second group of nets created in step 5 from U01 to U01_D2. This assumes that the DS33R41 reference designator was U01. If it is not U01, change U01_D1 appropriately.
8. Save the newly created netlist.

The newly created PCB netlist will actually contain two instances for the DS33R41 physical device. The first instance will describe the pin connections related to the DS33Z41 section; the second will describe pin connections related to the DS21458 section. The new netlist can be loaded into any JTAG test suite along with the two DS33R41 BSDL files and any associated test vectors.

Although the method documented here has been tested and verified to work properly, there can be some unforeseen complications with other netlist formats. If additional assistance is needed during JTAG boundary scan testing, please use the contact information below.

Table 1. Device Pins for DS33Z41 Die Only

Pin	Description	Pin	Description	Pin	Description
A1	VSS	J18	RXD[2]	P13	VSS
B16	VDD3.3	J19	RXD[0]	P14	SDMASK[1]
B17	VDD3.3	J20	VSS	P15	SRAS
B19	VDD3.3	K3	VSS	P16	SDA[11]
B20	VDD3.3	K5	VSS	P17	VDD1.8
C19	VDD3.3	K6	VSS	P18	SDMASK[2]
C20	REF_CLK	K7	VSS	P19	SDATA[18]
D10	VDD3.3	K8	VSS	P20	SDATA[19]
D15	VSS	K13	RMIIMIIS	R11	VSS
D18	VDD3.3	K14	TCLKE	R12	SDATA[12]
D19	VDD3.3	K15	TSERO	R13	SDATA[6]
D20	VDD3.3	K16	TBSYNC	R14	SCAS
E19	VDD3.3	K17	JTDI1	R15	SDCS
E20	MDC	K18	RX_DV	R16	SBA[0]
F11	VSS	K19	RX_CLK	R17	SDA[10]
F14	VSS	K20	RX_ERR	R18	SDATA[31]
F18	VDD3.3	L4	VSS	R19	VSS
F19	VDD3.3	L5	VSS	R20	VDD1.8

F20	MDIO	L6	VSS	T11	SDATA[13]
G4	VSS	L7	VSS	T12	SDATA[14]
G5	VSS	L8	VSS	T13	SDATA[5]
G7	VSS	L14	RCLKI	T14	VDD1.8
G12	VSS	L15	RBSYNC	T15	SWE
G13	JTMS1	L16	RSERI	T16	SDA[8]
G14	JTRST1	L17	DCEDTES	T17	SDA[0]
G15	MODEC[1]	L18	TX_CLK	T18	SDATA[16]
G16	VDD3.3	L19	TX_EN	T19	SDATA[27]
G18	QOVF	L20	TXD[0]	T20	SDATA[26]
G19	REF_CLKO	M5	VSS	U11	SDATA[15]
G20	VSS	M6	VSS	U12	SDATA[4]
H5	VSS	M7	VSS	U13	VSS
H6	VSS	M12	VSS	U14	SDCLKO
H7	VSS	M13	VDD1.8	U15	VSS
H8	VSS	M14	SDATA[3]	U16	SDA[1]
H9	VSS	M15	SDATA[1]	U17	SDA[4]
H10	VSS	M16	VSS	U18	SDATA[29]
H14	JTDO1	M17	VDD1.8	U19	SDATA[25]
H15	RST	M18	TXD[2]	U20	SDATA[24]
H16	CS	M19	TXD[1]	V11	SDATA[11]
H18	RXD[1]	M20	TXD[3]	V12	SDATA[10]
H19	RXD[3]	N12	VSS	V13	SDATA[8]
H20	VSS	N14	VDD1.8	V14	VSS
J6	VSS	N15	VDD1.8	V15	SDA[9]
J7	VSS	N16	VDD1.8	V16	SDA[7]
J8	VSS	N17	VDD1.8	V17	SDMASK[3]
J9	VSS	N18	VSS	V18	SDATA[30]
J15	VSS	N19	RX_CRS/CRS_DV	V19	SDATA[22]
J16	VDD1.8	N20	COL_DET	V20	VDD1.8
J17	JTCLK1	P12	VSS	W11	SDATA[0]
W12	SDATA[9]	W19	SDATA[20]	T16	SDA[6]
W13	SDATA[7]	W20	SDATA[23]	Y17	SDA[2]
W14	VDD1.8	Y11	SDATA[2]	Y18	VDD1.8
W15	SBA[1]	Y12	VSS	Y19	SDATA[28]
W16	SDA[5]	Y13	SDMASK[0]	Y20	SDATA[21]
W17	SDA[3]	Y14	SYSCCLKI		
W18	SDATA[17]	Y15	VDD1.8		

Table 2. Device Pins for DS21458 Die Only

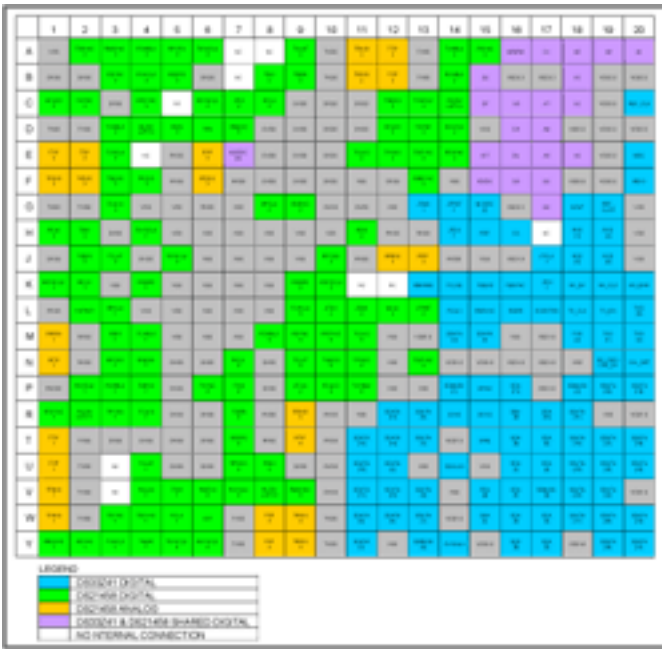
Pin	Description	Pin	Description	Pin	Description
A2	TSSYNC3	D3	TCHBLK3	G9	RNEGO2
A3	RMSYNC3	D4	RLOS/LOT3	G10	DVSS

A4	RCHBLK3	D5	RSIG3	G11	DVSS
A5	RPOSO3	D6	TPD	G17	D0
A6	TSYSCLK3	D7	RNEGO3	H1	RCLK3
A9	TCLK2	D8	DVDD	H2	TSIG3
A10	TVDD	D9	DVDD	H3	DVSS
A11	TRING2	D11	DVDD	H4	TSYSCLK1
A12	TTIP2	D12	RCLKO2	H11	RSIG2
A13	TVSS	D13	TSYNC2	H12	RVSS
A14	TCHBLK2	D14	RCHCLK2	H13	RVSS
A15	RSYNC2	E1	TTIP3	J1	DVSS
B1	DVSS	E2	TTIP3	J2	TSERI3
B2	DVSS	E3	TCHCLK3	J3	TCLKT3
B3	RSYNC3	E5	RVSS	J4	DVDD
B4	RCHCLK3	E6	RTIP3	J5	TSYSCLK2
B5	RSERO3	E8	DVDD	J10	RPOSO2
B6	DVDD	E9	DVDD	J11	RVSS
B8	TSIG2	E10	DVDD	J12	RRING2
B9	TSERI2	E11	TCLKO2	J13	RTIP2
B10	TVDD	E12	TPOSO2	J14	RVDD
B11	TRING2	E13	TSSYNC2	K1	RSYSCLK1
B12	TTIP2	E14	RFSYNC2	K2	MCLK1
B13	TVSS	F1	TRING3	K4	RSERO1
B14	RCHBLK2	F2	TRING3	K9	RSERO2
C1	RCLKO3	F3	TNEGO3	K10	RSYSCLK2
C2	TSYNC3	F4	TPOSO3	L1	RVSS
C3	DVSS	F5	RVSS	L2	TRTRST
C4	RFSYNC3	F6	RRING3	L3	BPCLK1
C6	RSYSCLK3	F7	RVDD	L9	TCHCLK4
C7	JTDI2	F8	DVDD	L10	JTDO2
C8	RCLK2	F9	DVDD	L11	JTMS2
C9	DVDD	F10	DVDD	L12	MCLK2
C10	DVDD	F12	DVSS	L13	JTRST2
C11	DVDD	F13	RMSYNC2	M1	RRING1
C12	TNEGO2	G1	TVDD	M2	RVSS
C13	TCHCLK2	G2	DVDD	M3	RSIG1
C14	RLOS/LOT4	G3	TCLKO3	M4	TCHBLK1
D1	TVSS	G6	RVSS	M8	RCHBLK4
D2	TVSS	G8	BPCLK2	M9	RSYNC4
M10	RFSYNC4	R5	DVSS	V6	RNEGO4
M11	TCLKO4	R6	DVSS	V7	RCHCLK4
N1	RTIP1	R7	TSERI4	V8	RLOS/LOT4
N2	RVSS	R8	RVDD	V9	RMSYNC4

N3	RPOS01	R9	RRING4	V10	DVSS
N4	RNEGO1	R10	RVSS	W1	TRING1
N5	DVSS	T1	TTIP1	W2	TVDD
N6	DVSS	T2	TVSS	W3	TSYNC1
N7	RCLK4	T3	DVSS	W4	TSSYNC1
N8	DVSS	T4	DVSS	W5	RCLK1
N9	TCLKT4	T5	DVSS	W6	CST
N10	TNEGO4	T6	DVSS	W7	TVSS
N11	TPOS04	T7	RSERO4	W8	TTIP4
N13	TSSYNC4	T8	RVSS	W9	TRING4
P1	RVDD	T9	RTOP4	W10	TVDD
P2	RCHCLK1	T10	RVSS	Y1	RMSYNC1
P3	RCHBLK1	U1	TTIP1	Y2	RSYNC1
P4	TNEGO1	U2	TVSS	Y3	TCHCLK1
P5	DVSS	U4	TCLKT1	Y4	TSERI1
P6	TSYNC4	U5	DVSS	Y5	TSYSCLK4
P7	TSIG4	U6	DVSS	Y6	RSYSCLK4
P8	DVSS	U7	RPOS04	Y7	TVSS
P9	JTCLK2	U8	RSIG4	Y8	TTIP4
P10	RCLKO4	U9	DVSS	Y9	TRING4
P11	TCHBLK4	U10	DVSS	Y10	TVDD
R1	RFSYNC1	V1	TRING1		
R2	RLOS/LOTC1	V2	TVDD		
R3	TPOS01	V4	RCLKO1		
R4	TCLKO1	V5	TSIG1		

Table 3. Shared Device Pins for DS33Z41 and DS21458 Die

Pin	Description	Pin	Description	Pin	Description
A16	WR/RW	C16	A9	E17	A6
A17	D1	C17	A7	E18	A4
A18	A5	C18	A2	F15	RD/DS
A19	A0	D16	D5	F16	D3
A20	A1	D17	A8	F17	D2
B15	D6	E7	MODEC[0]	G17	D0
B18	A3	E15	INT		
C15	D7	E16	D4		



[More Detailed Image](#) (PDF, kB)

Figure 1. DS33R41 400-ball BGA, color-coded pinout and die map.

References

If you have additional questions on the JTAG testing of the DS33R41, please contact the Telecommunication Applications support team by email, telecom.support@dalsemi.com, or telephone at 01-972-371-6555.

For more information about the DS33R41 Inverse-Multiplexing Ethernet Mapper with Integrated Quad Port T1/E1/J1 Transceiver, please consult the appropriate data sheet at: [T/E Carrier and Packetized Communications](#).

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